Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NP-SDMC Series

High Current TSPD

The NP−SDMC series of High Current Thyristor Surge Protection Devices (TSPD) protect sensitive electronic equipment from transient overvoltage conditions. The high current withstand of these devices offer protection in extreme environments and provide a solution for GR−1089 balanced “Y” configurations.

The NP−SDMC Series helps designers to comply with the various regulatory standards and recommendations including: GR−1089−CORE, IEC 61000−4−5, ITU K.20/K.21/K.45, IEC 60950, TIA−968−A, FCC Part 68, EN 60950, UL 1950.

Features

- Low Leakage (Transparent)
- High Surge Current Capabilities
- Precise Turn on Voltages
- These are Pb−Free Devices

Typical Applications

- Central Office
- Rugged Modems
- Bottom Element in “Y” Configurations

ELECTRICAL CHARACTERISTICS

Device	V_{DRM} V	$V_{(BO)}$ V	C_O, 2 V, 1 MHz pF (Max)	C_O, 50 V, 1 MHz pF (Max)
NP0720SDMCT3G	65	88	65	30
NP1300SDMCT3G	120	160	65	30
NP1500SDMCT3G	140	180	65	30
NP1800SDMCT3G	170	220	65	30
NP3100SDMCT3G	275	350	65	30

G in part number indicates RoHS compliance
Other protection voltages are available upon request
Symmetrical Protection − Values the same in both negative and positive excursions
(See V−I Curve on page 3)

ON Semiconductor®

http://onsemi.com

HIGH CURRENT (200A) BIDIRECTIONAL SURFACE MOUNT THYRISTOR

SMB
JEDEC DO−214AA
CASE 403C

MARKING DIAGRAM

A = Assembly Location
Y = Year
WW = Work Week
xxx = Specific Device Code (NPxxx0SDMC)
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NPxxxxSDMCT3G	SMB (Pb−Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Rating		Value	Unit
V_{DRM}	Repetitive peak off−state voltage: Rated maximum (peak) continuous voltage that may be applied in the off−state conditions including all dc and repetitive alternating voltage components.	NP0720SDMCT3G	±65	V
		NP1300SDMCT3G	±120	
		NP1500SDMCT3G	±140	
		NP1800SDMCT3G	±170	
		NP3100SDMCT3G	±275	
I_{PPS}	Nonrepetitive peak pulse current: Rated maximum value of peak impulse pulse current that may be applied.	2x10 μs, GR−1089−CORE	1000	A
		10x1000 μs, GR−1089−CORE	200	
I_{TSM}	Non−repetitive peak on−state current: Rated maximum (peak) value of ac power frequency on−state surge current which may be applied for a specified time or number of ac cycles.	0.0167s, 50/60 Hz, full sine wave	60	A
		0.1s, 50/60 Hz, full sine wave	30	
		1000s, 50/60 Hz, full sine wave	2.2	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS TABLE (T_A = 25°C unless otherwise noted)

Symbol	Rating		Min	Typ	Max	Unit
$V_{(BO)}$	Breakover voltage: The maximum voltage across the device in or at the breakdown region. V_{DC} = 1000 V, dv/dt = 100 V/μs	NP0720SDMCT3G			±88	V
		NP1300SDMCT3G			±160	
		NP1500SDMCT3G			±180	
		NP1800SDMCT3G			±220	
		NP3100SDMCT3G			±350	
$I_{(BO)}$	Breakover Current: The instantaneous current flowing at the breakover voltage.				800	mA
I_H	Holding Current: The minimum current required to maintain the device in the on−state.		150			mA
I_{DRM}	Off−state Current: The dc value of current that results from the application of the off−state voltage	V_D = 50 V			2	μA
		$V_D = V_{DRM}$			5	
V_T	On−state Voltage: The voltage across the device in the on−state condition. I_T = 2.2 A (pk), PW = 300 μs, DC = 2%				4	V
dv/dt	Critical rate of rise of off−state voltage: The maximum rate of rise of voltage (below V_{DRM}) that will not cause switching from the off−state to the on−state. Linear Ramp between 0.1 V_{DRM} and 0.9 V_{DRM}		±5			kV/μs
di/dt	Critical rate of rise of on−state current: rated value of the rate of rise of current which the device can withstand without damage.				±500	A/μs
C_O	Off−state Capacitance f = 1.0 MHz, V_d = 1.0 V_{RMS}, V_D = −2 Vdc				65	pF

THERMAL CHARACTERISTICS

Symbol	Rating	Value	Unit
T_{STG}	Storage Temperature Range	−65 to +150	°C
T_J	Operating Temperature Range	−40 to +150	°C
R_{0JA}	Thermal Resistance: Junction−to−Ambient Per EIA/JESD51−3, PCB = FR4 3”x4.5”x0.06” Fan out in a 3x3 inch pattern, 2 oz copper track.	90	°C/W

ELECTRICAL PARAMETER/RATINGS DEFINITIONS

Symbol	Parameter
V_{DRM}	Repetitive Peak Off−state Voltage
$V_{(BO)}$	Breakover Voltage
I_{DRM}	Off−state Current
$I_{(BO)}$	Breakover Current
I_H	Holding Current
V_T	On−state Voltage
I_T	On−state Current
I_{TSM}	Nonrepetitive Peak On−state Current
I_{PPS}	Nonrepetitive Peak Impulse Current
V_D	Off−state Voltage
I_D	Off−state Current

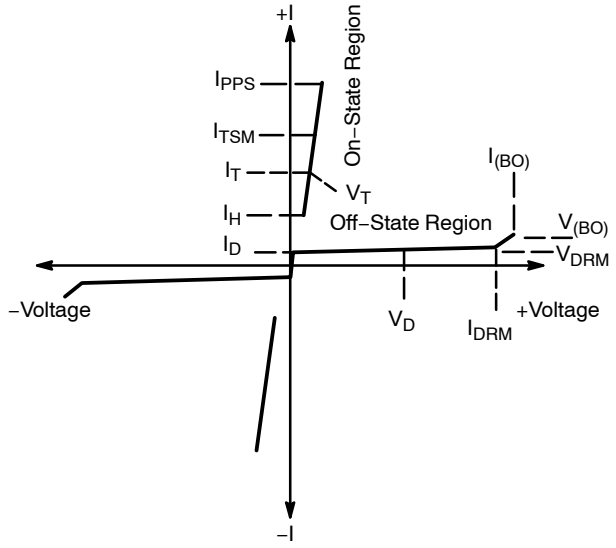


Figure 1. Voltage Current Characteristics of TSPD

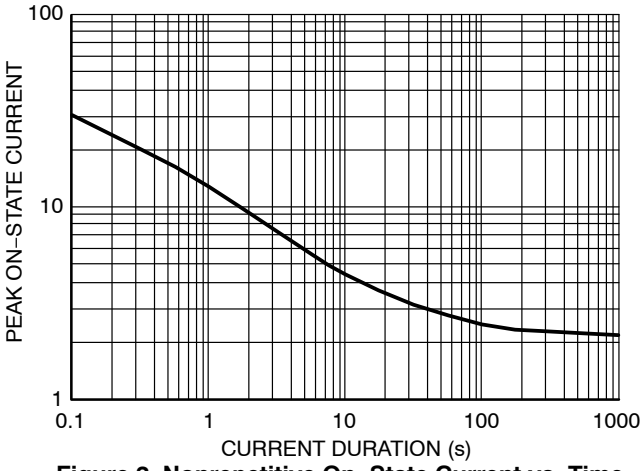


Figure 2. Nonrepetitive On−State Current vs. Time (I_{TSM})

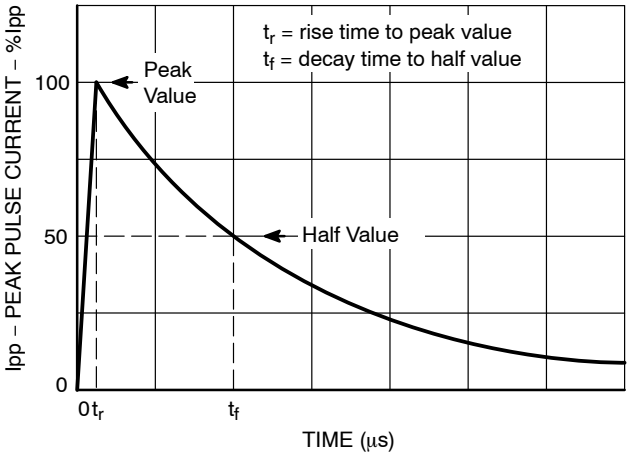


Figure 3. Nonrepetitive On−State Impulse vs. Waveform (I_{PPS})

Detailed Operating Description

The TSPD or Thyristor Surge Protection Device are specialized silicon based overvoltage protectors, used to protect sensitive electronic circuits from damaging overvoltage transient surges caused by induced lightning and powercross conditions.

The TSPD protects by switching to a low on state voltage when the specified protection voltage is exceeded. This is known as a “crowbar” effect. When an overvoltage occurs, the crowbar device changes from a high−impedance to a low−impedance state. This low−impedance state then offers a path to ground, shunting unwanted surges away from the sensitive circuits.

This crowbar action defines the TSPD’s two states of functionality: Open Circuit and Short Circuit.

Open Circuit – The TSPD must remain transparent during normal circuit operation. The device looks like an open across the two wire line.

Short Circuit – When a transient surge fault exceeds the TSPD protection voltage threshold, the devices switches on, and shorts the transient to ground, safely protecting the circuit.

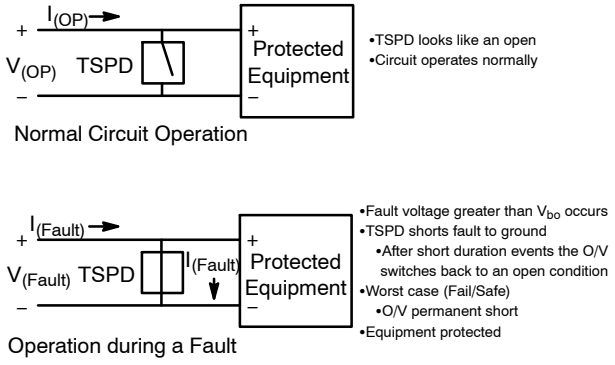


Figure 4. Normal and Fault Conditions

The electrical characteristics of the TSPD help the user to define the protection threshold for the circuit. During the open circuit condition the device must remain transparent; this is defined by the I_{DRM}. The I_{DRM} should be as low as possible. The typical value is less than 5 μA.

The circuit operating voltage and protection voltage must be understood and considered during circuit design. The $V_{(BO)}$ is the guaranteed maximum voltage that the protected circuit will see, this is also known as the protection voltage. The V_{DRM} is the guaranteed maximum voltage that will keep the TSPD in its normal open circuit state. The TSPD $V_{(BO)}$ is typically a 20−30% higher than the V_{DRM}. Based on these characteristics it is critical to choose devices which have a V_{DRM} higher than the normal circuit operating voltage, and a $V_{(BO)}$ which is less than the failure threshold of the protected equipment circuit. A low on−state voltage V_t allows the TSPD to conduct large amounts of surge current (500 A) in a small package size.

Once a transient surge has passed and the operating voltage and currents have dropped to their normal level the TSPD changes back to its open circuit state.

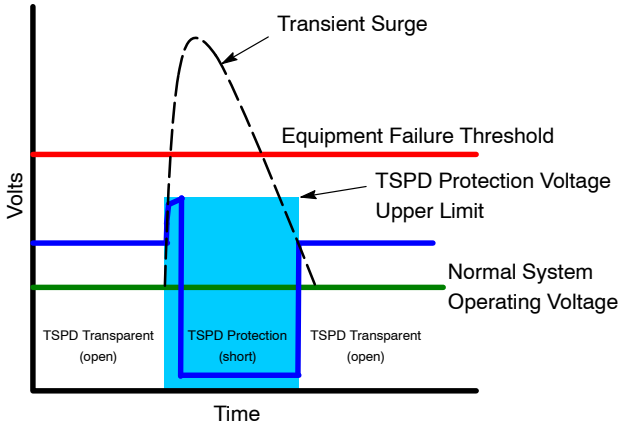


Figure 5. Protection During a Transient Surge

TSPD's are useful in helping designers meet safety and regulatory standards in Telecom equipment including GR−1089−CORE, ITU−K.20, ITU−K.21, ITU−K.45, FCC Part 68, UL1950, and EN 60950.

ON Semiconductor offers a full range of these products in the NP series product line.

DEVICE SELECTION

When selecting a TSPD use the following key selection parameters.

Off−State Voltage V_{DRM}

Choose a TSPD that has an Off−State Voltage greater than the normal system operating voltage. The protector should not operate under these conditions:

Example:

$$Vbat = 48\ Vmax$$

$$Vring = 150\ Vrms = 150*1.414 = 212\ V\ peak$$

V_{DRM} should be greater than the peak value of these two components:

$$V_{DRM} > 212 + 48 = 260\ V_{DRM}$$

Breakover Voltage $V_{(BO)}$

Verify that the TSPD Breakover Voltage is a value less than the peak voltage rating of the circuit it is protecting.

Example: Relay breakdown voltage, SLIC maximum voltage, or coupling capacitor maximum rated voltage.

Peak Pulse Current Ipps

Choose a Peak Pulse current value which will exceed the anticipated surge currents in testing.

Hold Current (I_H)

The Hold Current must be greater than the maximum system generated current. If it is not then the TSPD will remain in a shorted condition, even after a transient event has passed.

TYPICAL APPLICATION

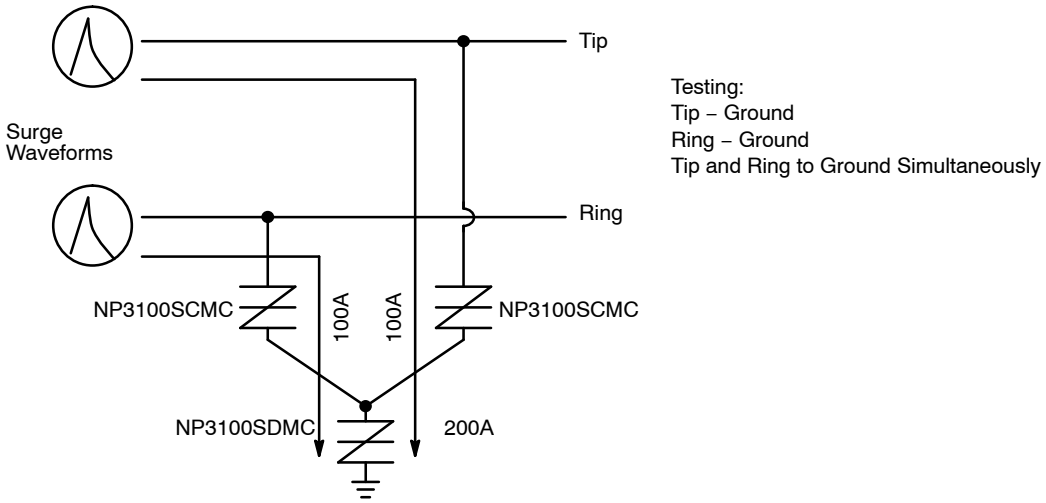
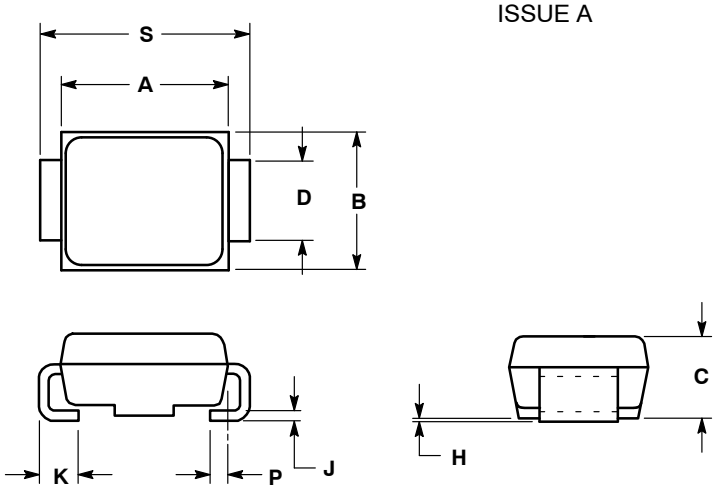


Figure 6.

- 200 A 10 x 1000 μs Needed for GR−1089
- Bottom Element in “Y” Configuration

PACKAGE DIMENSIONS

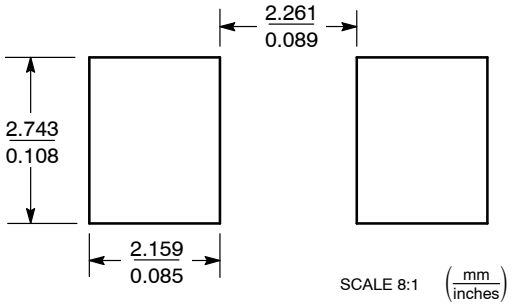
SMB
CASE 403C−01
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.130	0.150	3.30	3.81
C	0.075	0.095	1.90	2.41
D	0.077	0.083	1.96	2.11
H	0.0020	0.0060	0.051	0.152
J	0.006	0.012	0.15	0.30
K	0.030	0.050	0.76	1.27
P	0.020 REF		0.51 REF	
S	0.205	0.220	5.21	5.59

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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For additional information, please contact your local Sales Representative

NP3100SD/D